

Title (en)
METHOD FOR FITTING AN ELECTRICAL COMPONENT TO A CONTACTING ELEMENT AND CONTACTING ELEMENT WITH AN ELECTRICAL COMPONENT

Title (de)
VERFAHREN ZUM BESTÜCKEN EINES KONTAKTIERUNGSELEMENTES MIT EINEM ELEKTRISCHEN BAUELEMENT SOWIE EIN KONTAKTIERUNGSELEMENT MIT EINEM ELEKTRISCHEN BAUELEMENT

Title (fr)
PROCÉDÉ D'ÉQUIPEMENT D'UN ÉLÉMENT DE MISE EN CONTACT AVEC UN COMPOSANT ÉLECTRIQUE ET ÉLÉMENT DE MISE EN CONTACT COMPORTANT UN COMPOSANT ÉLECTRIQUE

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EP 2130419 A1 20091209 (DE)

Application
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Priority
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Abstract (en)
[origin: WO2008116677A1] The invention relates to a method for equipping a contacting element (1), in particular a punched grid with an SMD component (4), comprising the following steps: providing the contacting element (1) with a casing, a connector point (3) being provided in a recess (7) of the casing (5); placing the SMD component (4) on the connector point (3); and heating a thermally conductive element in order to heat the connector point (3) so that the SMD component (4) can be connected to the connector point (4).

IPC 8 full level
H05K 3/34 (2006.01); **H01L 23/495** (2006.01)

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Citation (search report)
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DOCDB simple family (application)
DE 102007014337 A 20070326; CN 200880009855 A 20080128; EP 08708260 A 20080128; EP 2008050937 W 20080128; JP 2010500155 A 20080128; US 53298108 A 20080128